



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

April 20, 2009

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING METHOD

Serial No.: 10/576 230

Group: 1792

Confirmation No.: 7180

Filed: April 14, 2006

Examiner: Bareford

International Application No.: PCT/JP2004/014049

International Filing Date: September 17, 2004

Atty. Docket No.: 4700.P0328US

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

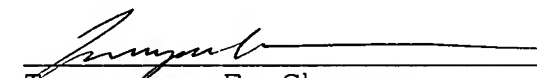
**LETTER TRANSMITTING APPEAL BRIEF FEE**

Sir:

Enclosed is Appellants' check in the sum of \$540.00, representing payment of the Appeal Brief fee. The Commissioner is hereby authorized to charge any additional fee which may be required by this paper, or to credit any overpayment, to Deposit Account No. 06-1382.

Respectfully submitted,

TFC/smd

  
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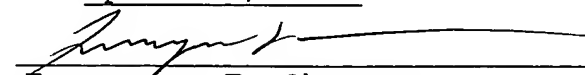
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\*limited recognition number

Encl: Check (\$540)  
Appellants' Brief on Appeal  
Claims Appendix  
Evidence Appendix  
Related Proceedings Appendix

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231 on April 20, 2009.

  
Terryence F. Chapman